

ABSTRACT OF THE DISCLOSURE

A method of manufacturing a monolithic ceramic electronic device includes the following steps: forming a first metal film_(12, 32, 112) on a PET film; forming a multilayered metal film_(15, 136) by forming a second metal film_(14, 34, 114) on a part of the first metal film, the second metal film being thicker than the first metal film; forming a monolithic ceramic structure_(13, 113) including the multilayered metal film; forming a portion of the first metal film, which is overlain by the second metal film in the monolithic ceramic structure, into an insulating structure in such a manner that metal components forming the part are diffused into ceramics; and firing the ceramics. Disclosed also is a monolithic ceramic electronic device manufactured by the method. As a result, a stepped portion between a portion in which the internal electrodes overlap one another and a portion in which the internal electrodes do not overlap can be prevented from being formed, generation of delamination can effectively be prevented, whereby a monolithic ceramic electronic device exhibiting stable characteristics and a method for manufacturing the monolithic ceramic electronic device can be obtained.

